

Chip Bead For High Current

CIC21 Series (2012/ EIA 0805)



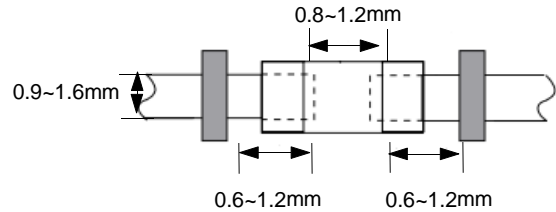
APPLICATION

Noise Suppression in power line

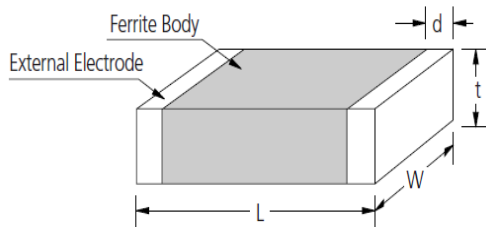
FEATURES

- CIC series is used for high current.)

RECOMMENDED LAND PATTERN



DIMENSION

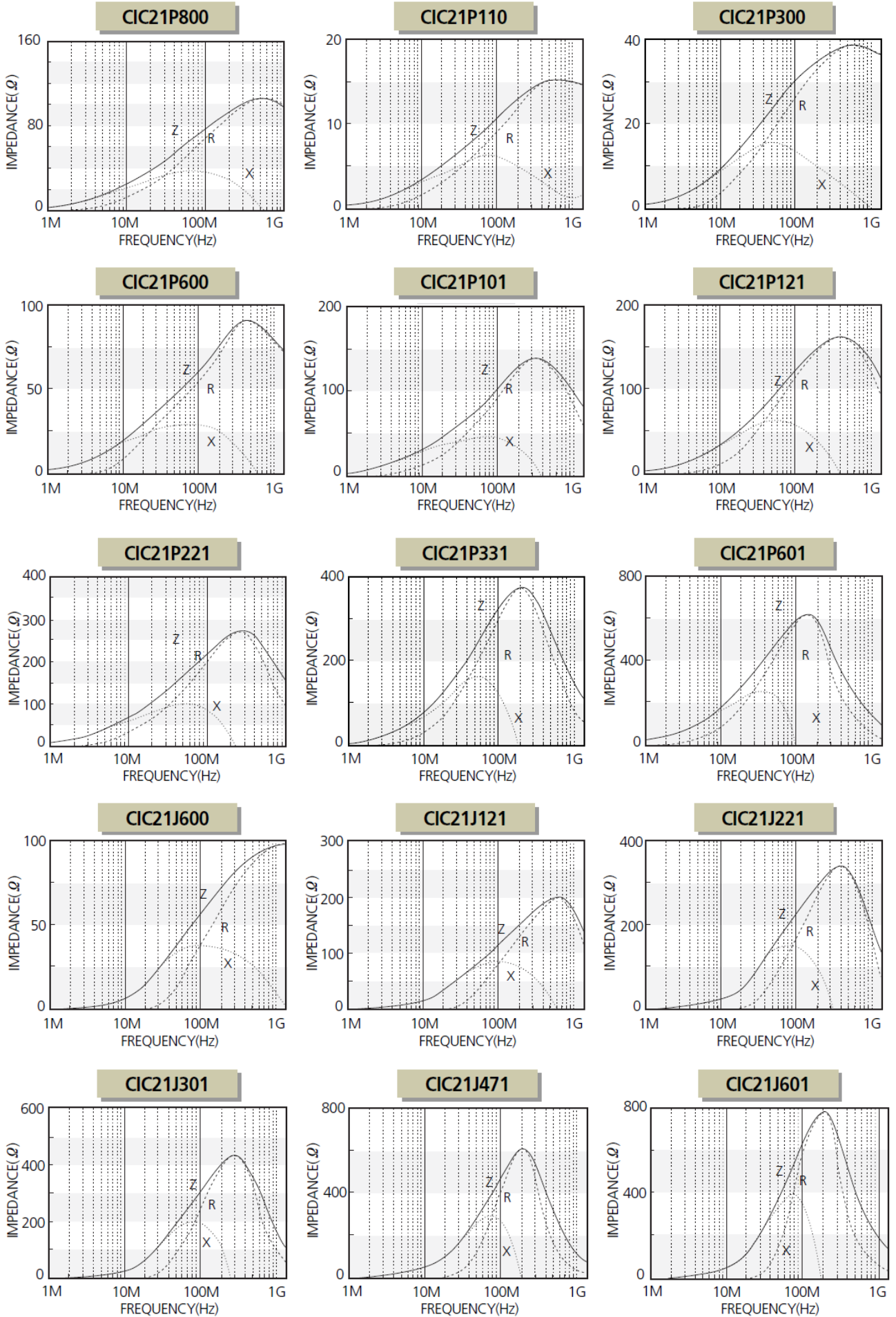


Type	Dimension [mm]			
	L	W	t	d
21	2.0±0.2	1.25±0.2	0.9±0.2	0.5+0.2 -0.3

DESCRIPTION

Part no.	Thickness (mm)	Impedance (Ω)±25%@100MHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIC21P110	0.90±0.2	11	0.05	6000
CIC21P300	0.90±0.2	30	0.015	3000
CIC21P600	0.90±0.2	60	0.025	3000
CIC21P800	0.90±0.2	80	0.025	2500
CIC21P101	0.90±0.2	100	0.02	2000
CIC21P121	0.90±0.2	120	0.05	2000
CIC21P221	0.90±0.2	220	0.035	3200
CIC21P331	0.85±0.2	330	0.05	2000
CIC21P601	0.90±0.2	600	0.15	1000
CIC21J600	0.90±0.2	60	0.03	3800
CIC21J121	0.90±0.2	120	0.05	2500
CIC21J221	0.90±0.2	220	0.05	1500
CIC21J301	0.90±0.2	300	0.10	1500
CIC21J471	0.90±0.2	470	0.08	1500
CIC21J601	0.90±0.2	600	0.15	1000

CHARACTERISTIC DATA



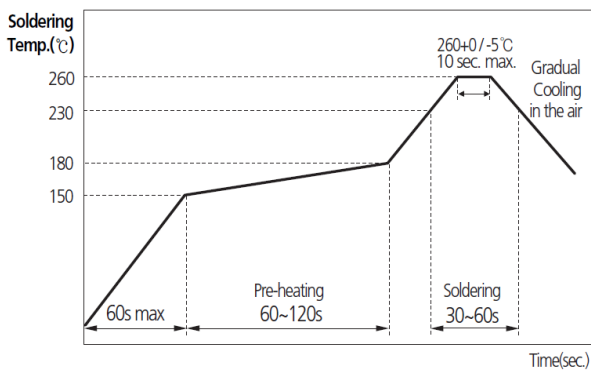
PRODUCT IDENTIFICATION

CI C 21 P 110 N E
(1) (2) (3) (4) (5) (6) (7)

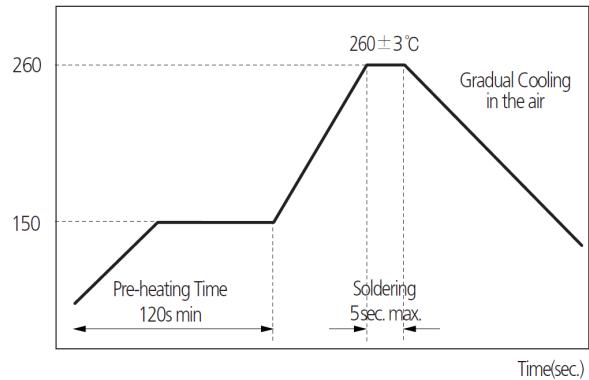
- (1) Chip Beads
- (2) For High current(C:~3A)
- (3) Dimension
- (4) Material Code
- (5) Nominal impedance (110:11Ω, 221:220Ω)
- (6) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (7) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING




FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Embossed Taping	4000

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The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers.